



4 Pad Ceramic Package Quartz Crystal, 5.0mm x 3.2mm



ILCX07 Series

Product Features:

Low Cost SMD Package
Low ESR
Compatible with Leadfree Processing

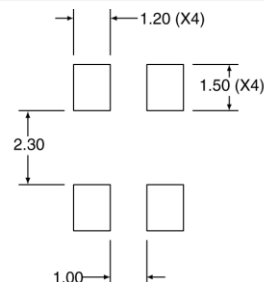
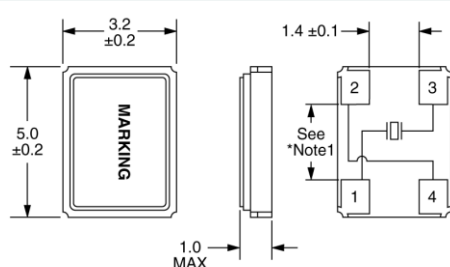
Applications:

Fibre Channel
Server & Storage
Sonet / SDH
802.11 / WiFi
T1/E1, T3/E3

Electrical Specifications

Frequency	8MHz to 150MHz
Equivalent Series Resistance 8MHz – 9.999999MHz 10MHz – 11.999999MHz 12MHz – 15.999999MHz 16MHz – 19.999999MHz 20MHz – 23.999999MHz 24MHz – 50MHz 30MHz – 150MHz (Third Overtone)	100 Ohms Maximum 80 Ohms Maximum 60 Ohms Maximum 50 Ohms Maximum 40 Ohms Maximum 30 Ohms Maximum 80 Ohms Maximum
Shunt Capacitance (C0)	5pF Maximum
Frequency Tolerance (at 25°C)	±50ppm, ±30ppm, ±25ppm, ±20ppm, ±15ppm, or ±10ppm
Frequency Stability (over Temperature)	±50ppm, ±30ppm, ±25ppm, ±20ppm, ±15ppm, or ±10ppm
Mode of Operation 8MHz – 50MHz 30MHz – 150MHz	Fundamental Third Overtone
Crystal Cut	AT Cut
Load Capacitance	8pF to 32pF or Specify
Drive Level	100µW Maximum
Aging	±5ppm/Year Maximum
Operating Temperature Range	See Part Number Guide
Storage Temperature Range	-40°C to +85°C

Mechanical and Solder Pad Dimensions



Pin	Connection
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

All Dimensions in Millimeters

Note: Chamfer not shown

*Note 1: 2.6 ±0.1mm (<= 10MHz)
2.4 ±0.1mm (> 10MHz)

Part Number Guide

Sample Part Number: ILCX07 – FB1F18 – 20.000 MHz

Package	Frequency Tolerance	Frequency Stability	Operating Temperature Range	Mode of Operations	Load Capacitance	Frequency
ILCX07 -	B = ±50ppm	B = ±50ppm	0 = 0°C to +50°C	F = Fundamental	8pF to 32pF or Specify	20.000 MHz
	F = ±30ppm	F = ±30ppm	1 = 0°C to +70°C	3 = Third Overtone		
	G = ±25ppm	G = ±25ppm	2 = -10°C to +60°C			
	H = ±20ppm	H = ±20ppm	3 = -20°C to +70°C			
	I = ±15ppm	I = ±15ppm*, **	5 = -40°C to +85°C			
	J = ±10ppm*	J = ±10ppm*, **	9 = -10°C to +50°C			
			D = -10°C to +105°C*			
			E = -40°C to +105°C*			

* Not available at all frequencies. ** Not available for all temperature ranges.

**QUALITY SYSTEM
CERTIFIED
= ISO 9001 =**

ILSI America Phone 775-851-8880 • Fax 775-851-8882 • email: e-mail@ilsiamerica.com •

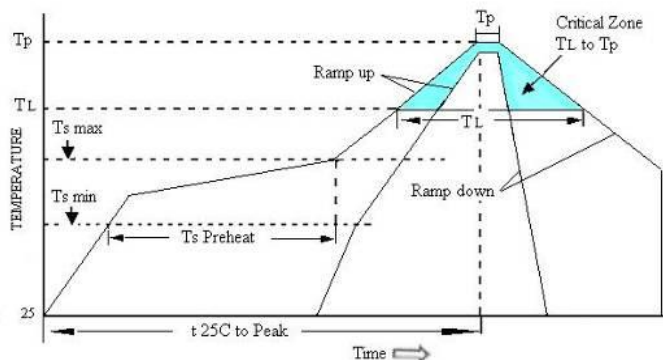
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Specifications subject to change without notice

Rev: 04/17/18_D

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Pb Free Solder Reflow Profile:



Units are backward compatible with +240°C reflow processes

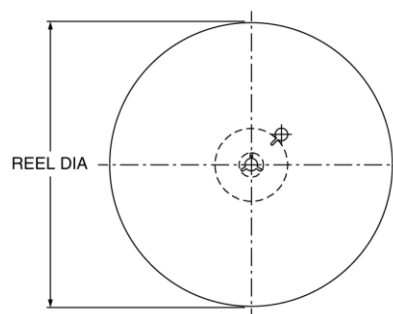
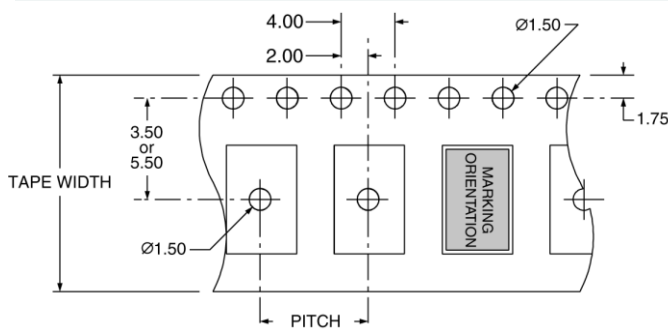
Ts max to T _L (Ramp-up Rate)	3°C / second max
Preheat	
Temperature min (Ts min)	150°C
Temperature typ (Ts typ)	175°C
Temperature max (Ts max)	200°C
Time (Ts)	60 to 180 seconds
Ramp-up Rate (T _L to Tp)	3°C / second max
Time Maintained Above Temperature (T _L)	
Time (T _L)	217°C
Peak Temperature (Tp)	60 to 150 seconds
Time within 5°C to Peak Temperature (Tp)	260°C max for 10 seconds
Ramp-down Rate	20 to 40 seconds
Time 25°C to Peak Temperature	6°C / second max
	8 minutes max

Package Information:

MSL = 1 (package does not contain plastic, storage life is unlimited under normal room conditions)

Termination = e4 (Au over Ni over W base metallization)

Tape and Reel Information:



PITCH	8.00
TAPE WIDTH	12.00
REEL DIA	180
QTY PER REEL	1,000

All Dimensions in Millimeters

Environmental Specifications:

Mechanical Shock	MIL-STD-202, Method 213
Vibration	MIL-STD-202, Method 204
Resistance to Soldering Heat	MIL-STD-202, Method 210
Solderability	J-STD-002
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2

Marking:

Line 1: ILSI, Date Code (YWW)

Line 2: Frequency